

Replace the paragraph beginning at page 1, line 28 with:

A² However, such a marking and its curing require a lot of time, and also it is not easy to handle with the ink, so that an increasing number of manufacturers have adopted a laser mark 6.

Replace the paragraph beginning at page 2, line 3 with:

A³ Further, although there have been some reports on improvement in the visibility of a laser mark, they are not reported as quantitative values, and it is not clear whether they are good or poor.

IN THE CLAIMS:

Replace the indicated claims with:

1. (Amended) An epoxy resin composition that seals a semiconductor chip, wherein a color difference between a color of said epoxy resin and a color of a standard substance stored in a colorimeter has a value of at least 30.

2. (Amended) An epoxy resin composition that seals a semiconductor chip, said epoxy resin composition including an epoxy resin and a filler that fills said epoxy resin, wherein said filler contains from 10 to 15 wt%, with respect to total filler, of a filler component having an average particle size of no more than 10 μm .

Sub C 3. (Amended) A semiconductor device including:
a semiconductor chip;
a package of an epoxy resin encapsulating said semiconductor chip; and
a laser mark printed on a surface of said package, wherein a color difference between a color of said laser mark and a color of the surface of said package where the laser mark is not present, as measured by a colorimeter, has a value of at least 10.

4. (Amended) A semiconductor device including:
a semiconductor chip;
a package of an epoxy resin encapsulating said semiconductor chip; and